

AMENDMENTS TO THE CLAIMS

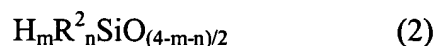
1. (currently amended) A semiconductor encapsulating flame retardant epoxy resin composition comprising:

(A) an epoxy resin,

(B) a phenolic resin curing agent,

(C) zinc molybdate supported on an inorganic carrier,

(D) at least one organopolysiloxane (D-iii) block copolymer obtained by reacting an epoxy resin or an alkenyl group-bearing epoxy resin with an organopolysiloxane of the following average compositional formula (2):



wherein R^2 is a substituted or unsubstituted monovalent hydrocarbon group, m is a positive number of 0.001 to 0.2, n is a positive number of 1.8 to 2.1, and m+n is 1.801 to 2.3, the number of silicon atoms in a molecule is an integer of 10 to 1000, and the number of hydrogen atoms directly attached to silicon atoms is 1 to 5, addition reaction taking place between epoxy groups on the epoxy resin or alkenyl groups on the alkenyl group-bearing epoxy resin and silicon-attached hydrogen atoms on the organopolysiloxane, and

(E) an inorganic filler

said composition being free of halogenated epoxy resins and of antimony compounds.

2. (original) The epoxy resin composition of claim 1, wherein the amount of phenolic hydroxyl groups in curing agent (B) is from 0.5 to 1.5 moles per mole of epoxy groups in epoxy resin (A).

3. (original) The epoxy resin composition of claim 1, wherein the zinc molybdate content of the inorganic carrier and zinc molybdate component amounts to 5 to 40% by weight.

4. (original) The epoxy resin composition of claim 3, wherein the zinc molybdate on inorganic carrier has a zinc molybdate content of 10 to 30% by weight.

5. (original) The epoxy resin composition of claim 1, wherein 1 to 120 parts by weight of the zinc molybdate on inorganic carrier is present per 100 parts by weight of components (A) and (B) combined.

6. (original) The epoxy resin composition of claim 1, wherein 1 to 10 parts by weight of the organosilicon compound (D-iii) is present per 100 parts by weight of components (A) and (B) combined.

7. (original) The epoxy resin composition of claim 6, wherein the amount of silicon compound (D-iii) is 2 to 8 parts by weight of the epoxy resin (A) and the curing agent (B) combined.

8. (original) The epoxy resin composition of claim 1, wherein the inorganic filler (E) is a spherical fused silica having a mean particle diameter of 1 to 40 μm .

9. (original) A semiconductor device encapsulated with a cured product of the epoxy resin composition of any one of claims 1 to 9.